SN54ACT16374... WD PACKAGE

74ACT16374 ... DL PACKAGE

(TOP VIEW)

1 OE 1

1Q1 2

1Q2 🛛 3

GND 4

1Q3 **1**5

1Q4 **6**

1Q5 8

1Q6 🛛 9

GND 10

1Q7 11

1Q8 12

2Q1 1 13

2Q2 1 14

GND 15

2Q3 16

2Q4 17

V_{CC} [] 18

GND 21

2Q7 [

2Q8 23

2OE

19 2Q6 🛛 20

22

24

2Q5

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48 🛛 1CLK

47 01D1

46 1D2

45 🛛 GND

44**1**1D3

43 1 1 D 4 42 VCC

41 1D5

40 1D6

39 GND

38] 1D7

37 1 1D8

36 2D1

35 1 2D2

34 🛛 GND

33 1 2D3

32 2D4

31 VCC

30 2D5

29 2D6

28 GND

27 12D7

26 2D8

25 25 2CLK

- **Members of the Texas Instruments** Widebus[™] Family
- Inputs Are TTL-Voltage Compatible
- 3-State Bus-Driving True Outputs
- **Flow-Through Architecture Optimizes PCB** Layout
- Distributed Center-Pin V_{CC} and GND **Configurations Minimize High-Speed** Switching Noise
- **EPIC[™]** (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center **Pin Spacings**

description

·com.c The SN54ACT16374 and 74ACT16374 are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports bidirectional bus drivers, and working registers. ports,

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

An output-enable input $\overline{(OE)}$ can be used to place the outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state provides the capability to drive bus lines in a bus-organized system without need for interface or pullup components. OE does not affect the internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16374 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit board area.

The SN54ACT16374 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT16374 is characterized for operation from -40°C to 85°C.



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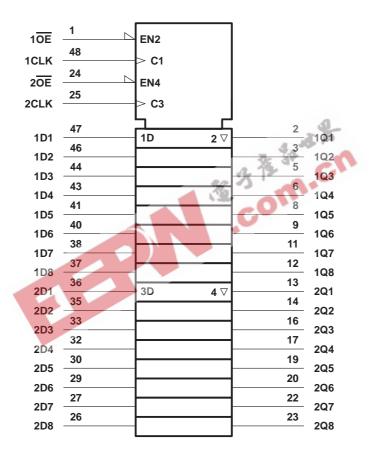


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FUNCTION TABLE (each section)								
	INPUTS	OUTPUT						
OE	CLK	D	Q					
L	\uparrow	Н	Н					
L	\uparrow	L	L					
L	H or L	Х	Q ₀					
н	Х	Х	Z					

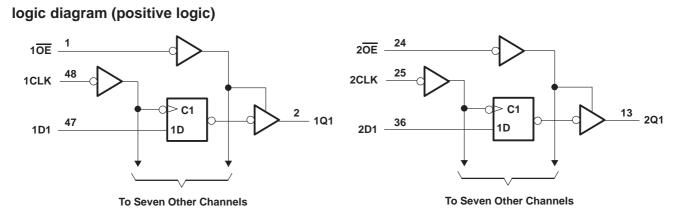
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Output voltage range, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		SN54ACT16374		74ACT16374			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage (see Note 4)	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
VI	Input voltage	0		VCC	0		VCC	V
Vo	Output voltage	0		VCC	0		VCC	V
ЮН	High-level output current			-24			-24	mA
IOL	Low-level output current			24			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	0		10	ns/V
ТА	Operating free-air temperature	-55		125	-40		85	°C

NOTES: 3. Unused inputs must be held high or low to prevent them from floating.

4. All $V_{\mbox{CC}}$ and GND pins must be connected to the proper voltage supply.



SN54ACT16374, 74ACT16374 16-BIT D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS SCAS124B – MARCH 1990 – REVISED APRIL 1996

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS	N.	Τį	λ = 25°C	;	SN54ACT	16374	74ACT	LINUT	
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		4.5 V	4.4			4.4		4.4		
	I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4		
	I _{OH} = -24 mA	4.5 V	3.94			3.7		3.8		
VOH	10H = -24 m/	5.5 V	4.94			4.7		4.8		V
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85				
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85		
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V
	$IOL = 30 \ \mu A$	5.5 V			0.1		0.1		0.1	
	I _{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
VOL		5.5 V			0.36		0.5		0.44	
	$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V					1.65			
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65	
lj	$V_{I} = V_{CC}$ or GND	5.5 V			±0.1	16- 1	±1		±1	μΑ
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V		1.3	±0.5		±10		±5	μΑ
lcc	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V	- 30	3	8		160		80	μΑ
ΔI_{CC}^{\ddagger}	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		C	0.9		1		1	mA
C _i	V _I = V _{CC} or GND	5 V		4.5						pF
Co	$V_{O} = V_{CC} \text{ or } GND$	5 V		12						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			T _A =	25°C	SN54AC	Г16374	74ACT	16374	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency		0	65	0	65	0	65	MHz
	Pulse duration	CLK low	7.5		7.5		7.5		
t _w		CLK high	4.5		4.5		4.5		ns
t _{su}	Setup time, data before $CLK\uparrow$		6.5		6.5		6.5		ns
t _h	Hold time, data after CLK^\uparrow		1		1		1		ns

SN54ACT16374, 74ACT16374 16-BIT D-TYPE EDGE-TRIGGERED FLIP-FLOPS WITH 3-STATE OUTPUTS SCAS124B – MARCH 1990 – REVISED APRIL 1996

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

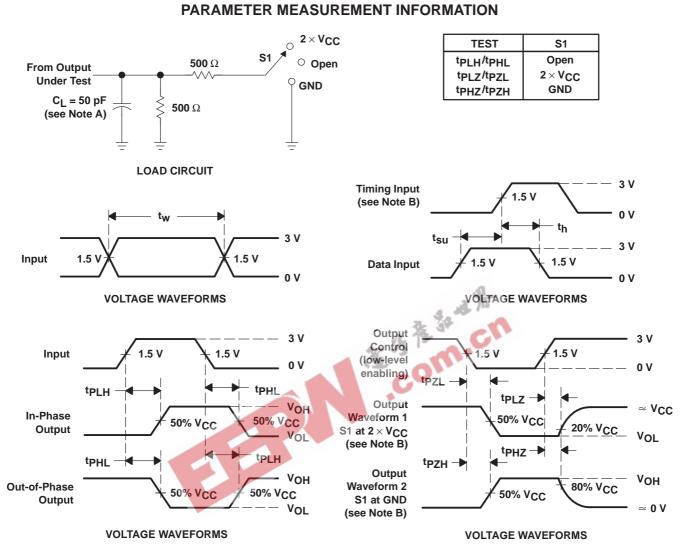
PARAMETER	FROM	то	T,	₄ = 25°C	;	SN54AC	Г16374	74ACT	16374	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
fmax			65			65		65		MHz
^t PLH	CLK	0	5.1	8.8	10.9	5.1	13.2	5.1	12.4	
^t PHL	ULK	Q	5.3	8.8	10.9	5.3	13.1	5.3	12.2	ns
^t PZH	OE	0	3.7	8.4	10.5	3.7	12.7	3.7	11.9	
^t PZL	ÛE	Q	4.4	9.7	11.9	4.4	14.3	4.4	13.4	ns
^t PHZ	OE	Q	5.4	7.9	9.8	5.4	10.9	5.4	10.4	ns
^t PLZ	ÛE	g	4.9	7.2	9.1	4.9	10.2	4.9	9.8	115

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	TYP	UNIT		
	Power dissipation capacitance per flip-flop	Outputs enabled	С _L = 50 рF,	f = 1 MHz	52	рF
Cpd	Power dissipation capacitance per hip-hop	Outputs disabled	CL = 50 μr,	I = I I V I I I Z	38	pr
		S TE SE	<u>cn</u>			



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NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 3 ns, t_f = 3 ns.

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9202501MXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC
74ACT16374DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16374DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16374DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ACT16374WD	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

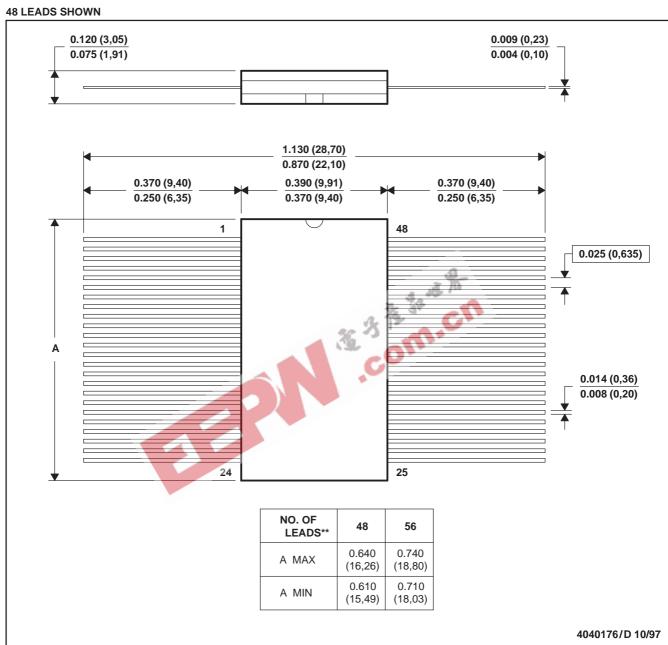
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MECHANICAL DATA

MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).

WD (R-GDFP-F**)

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO -146AA GDFP1-F56 and JEDEC MO -146AB

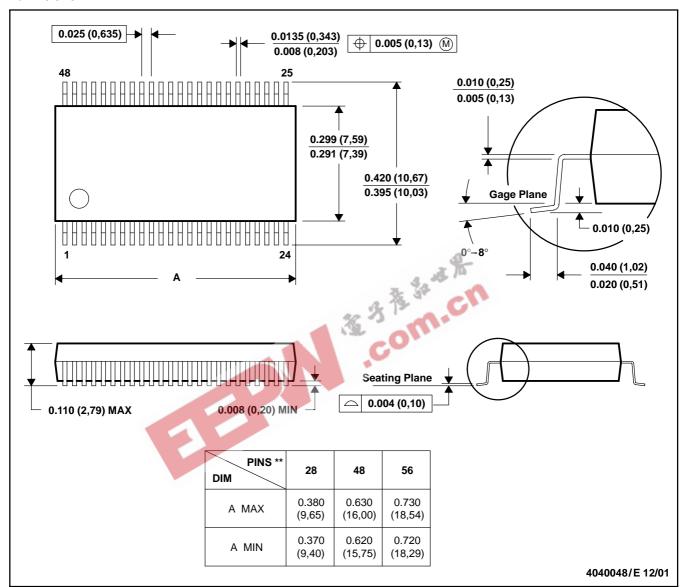


MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

DL (R-PDSO-G**) 48 PINS SHOWN



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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